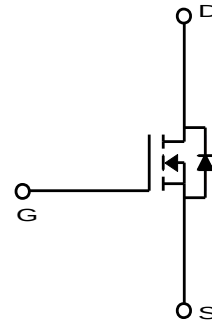
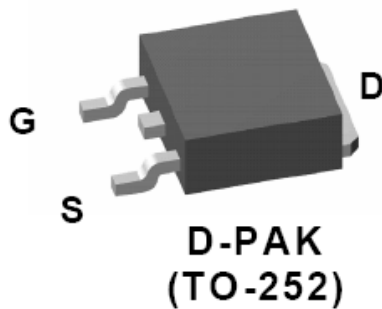


General Description

The MDD1901 uses advanced Magnachip's MOSFET Technology, which provides high performance in on-state resistance, fast switching performance and excellent quality. MDD1901 is suitable device for DC/DC Converters and general purpose applications.

Features

- $V_{DS} = 100V$
- $I_D = 40A$ @ $V_{GS} = 10V$
- $R_{DS(ON)} < 22m\Omega$ @ $V_{GS} = 10V$
- $< 25m\Omega$ @ $V_{GS} = 6.0V$



Absolute Maximum Ratings ($T_c = 25^\circ C$)

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	100	V
Gate-Source Voltage		V_{GSS}	± 20	V
Continuous Drain Current ⁽¹⁾	$T_C = 25^\circ C$	I_D	40	A
	$T_C = 100^\circ C$		24	A
Pulsed Drain Current		I_{DM}	80	A
Power Dissipation	$T_C = 25^\circ C$	P_D	70	W
	$T_C = 100^\circ C$		28	
Single Pulse Avalanche Energy ⁽²⁾		E_{AS}	200	mJ
Junction and Storage Temperature Range		T_J, T_{stg}	-55~150	$^\circ C$

Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	40	$^\circ C/W$
Thermal Resistance, Junction-to-Case ⁽¹⁾	$R_{\theta JC}$	1.8	

Ordering Information

Part Number	Temp. Range	Package	Packing	Rohs Status
MDD1901RH	-55~150°C	D-PAK	Tape & Reel	Halogen Free

Electrical Characteristics (Tc =25°C)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V	100	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.0	2.8	4.0	
Drain Cut-Off Current	I _{DSS}	V _{DS} = 80V, V _{GS} = 0V	-	-	1	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±0.1	
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 35A	-	17	22	mΩ
		T _J =125°C	-	28	33	
		V _{GS} = 6.0V, I _D = 20A		19	25	
Forward Transconductance	g _{fs}	V _{DS} = 5V, I _D = 35A	-	35	-	S
Dynamic Characteristics						
Total Gate Charge	Q _g	V _{DS} = 50V, I _D = 20A, V _{GS} = 10V	-	75	100	nC
Gate-Source Charge	Q _{gs}		-	12	-	
Gate-Drain Charge	Q _{gd}		-	20	-	
Input Capacitance	C _{iss}	V _{DS} = 30V, V _{GS} = 0V, f = 1.0MHz	-	3090	-	pF
Reverse Transfer Capacitance	C _{rss}		-	160	-	
Output Capacitance	C _{oss}		-	235	-	
Gate Resistance	R _g	V _{GS} =0V,V _{DS} =0V,F=1MHz	-	0.8	-	Ω
Turn-On Delay Time	t _{d(on)}	V _{DS} =50V, V _{GS} =10V, R _L =1.15Ω, R _{GEN} =2.5Ω	-	15	21	ns
Rise Time	t _r		-	26	36	
Turn-Off Delay Time	t _{d(off)}		-	69	96	
Fall Time	t _f		-	15	21	
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	V _{SD}	I _S = 1A, V _{GS} = 0V	-	0.7	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 20A, dI/dt = 100A/μs	-	70	100	ns
Body Diode Reverse Recovery Charge	Q _{rr}		-	240	-	nC

Note :

1. Surface mounted RF4 board with 2oz. Copper.
2. Starting $T_J=25^\circ C, L=1mH, I_{AS}=20A, V_{DD}=50V, V_{GS}=10V$

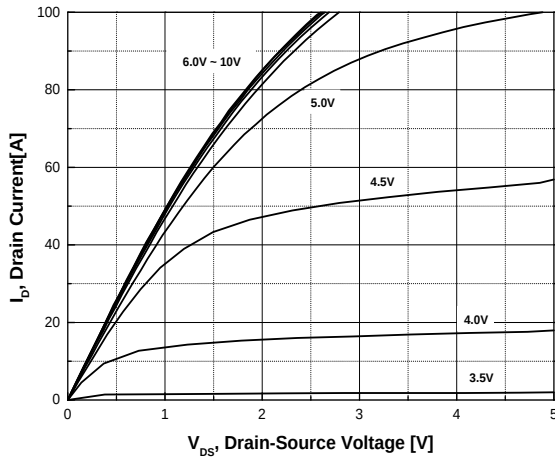


Fig.1 On-Region Characteristics

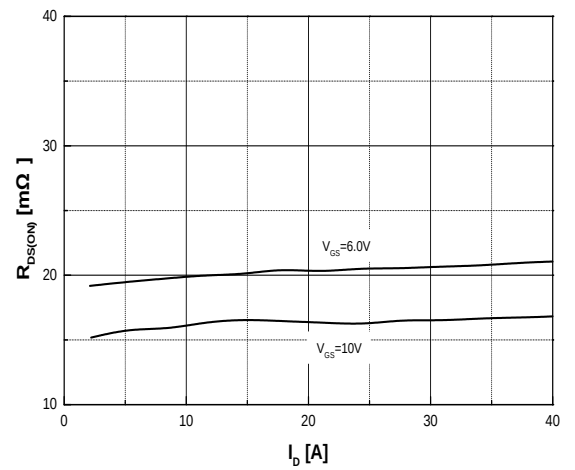


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

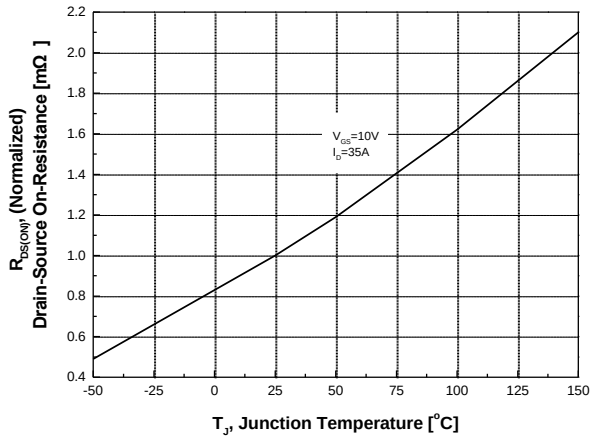


Fig.3 On-Resistance Variation with Temperature

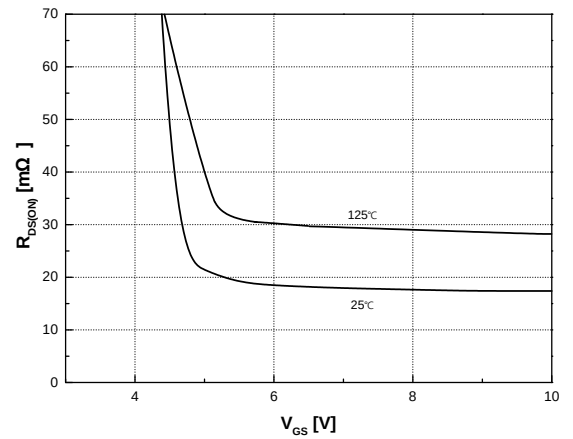


Fig.4 On-Resistance Variation with Gate to Source Voltage

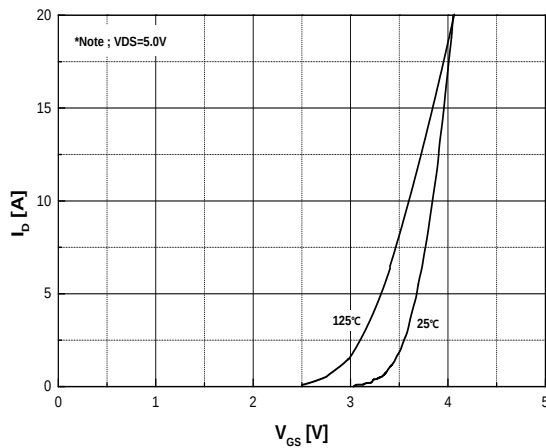


Fig.5 Transfer Characteristics

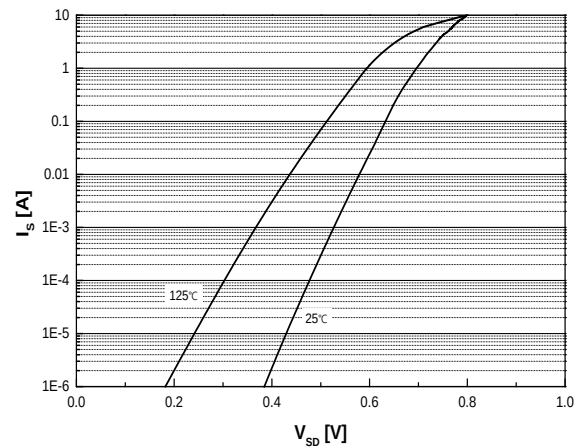


Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature

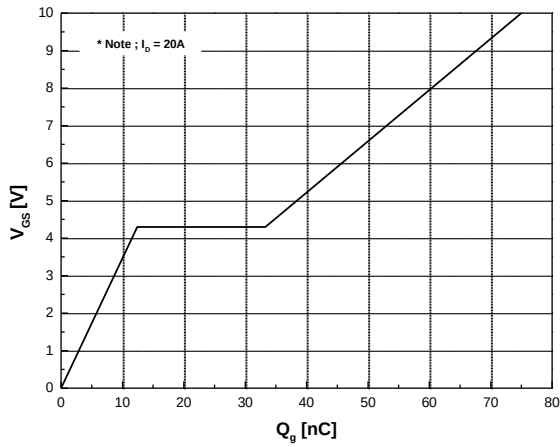


Fig.7 Gate Charge Characteristics

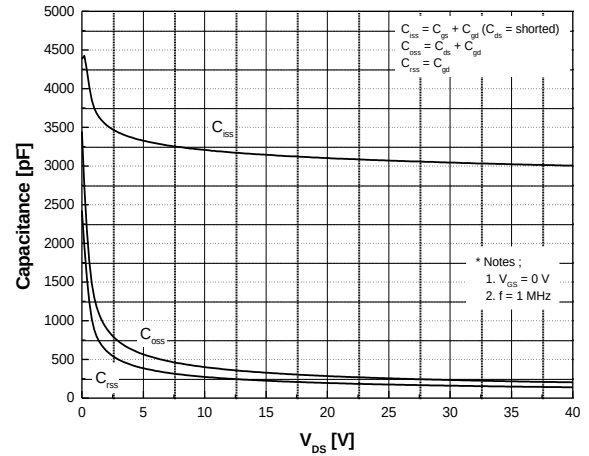


Fig.8 Capacitance Characteristics

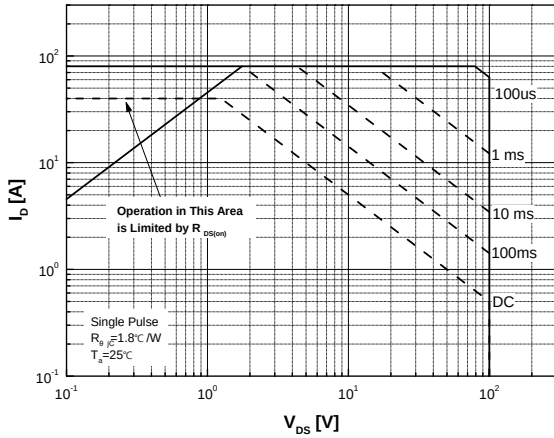


Fig.9 Maximum Safe Operating Area

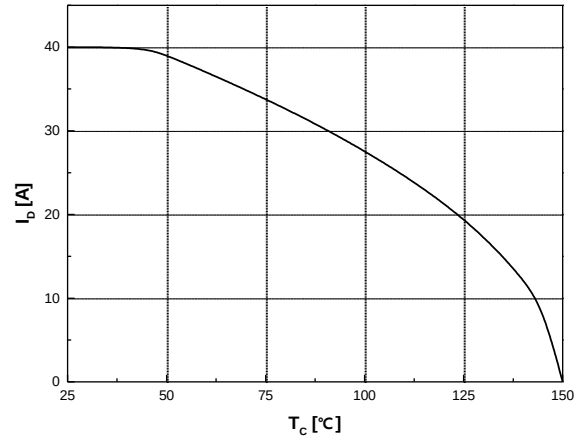


Fig.10 Maximum Drain Current vs. Case Temperature

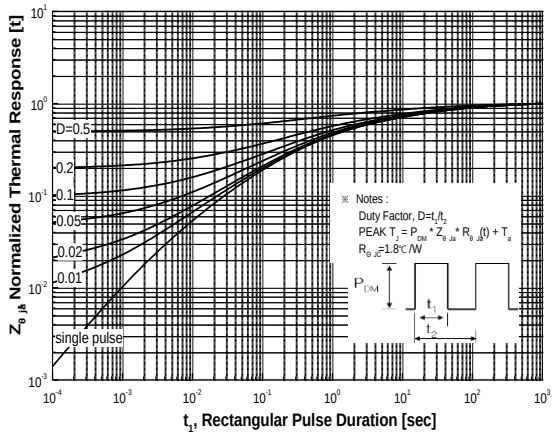
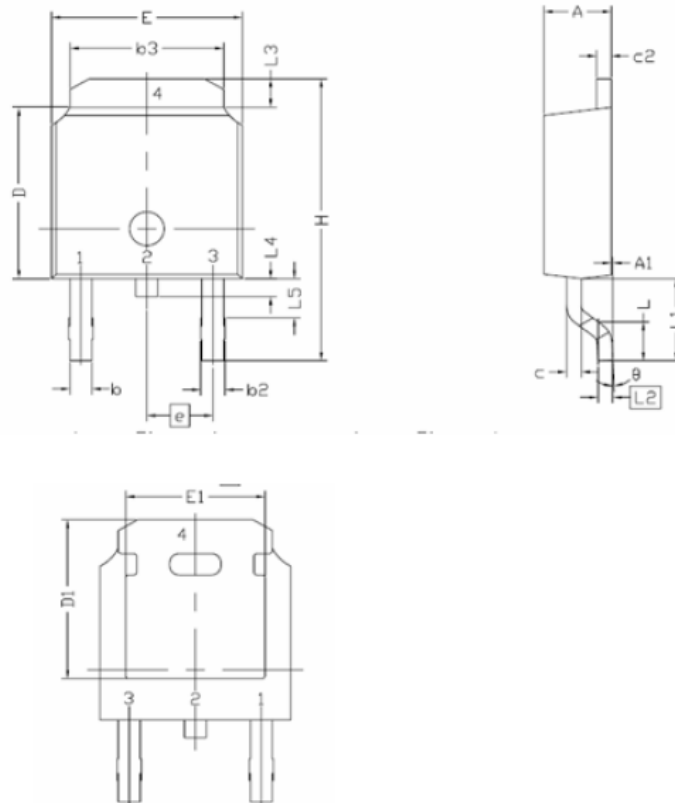


Fig.11 Transient Thermal Response Curve

Package Dimension

D-PAK (TO-252)

Dimensions are in millimeters, unless otherwise specified



Symbol	Min.	Nom.	Max.
E	6,35	—	6,73
L	1,40	1,52	1,78
L1	2,74 REF		
L2	0,508 BCS		
L3	0,89	—	1,27
L4	—	—	1,02
L5	1,14	—	1,52
D	5,97	6,10	6,22
H	9,40	—	10,41
b	0,64	—	0,89
b2	0,76	—	1,14
b3	4,95	—	5,46
e	2,286 BSC		
A	2,18	—	2,39
A1	—	—	0,13
c	0,46	—	0,61
c2	0,46	—	0,89
D1	5,21	—	—
E1	4,32	—	—
⌀	0,00	—	10,00

Note : Package body size, length and width do not include mold flash, protrusions and gate burrs.

DISCLAIMER:

The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.

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